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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	M8C
Core Size	8-Bit
Speed	12MHz
Connectivity	I²C, IrDA, SPI, UART/USART
Peripherals	LVD, POR, PWM, WDT
Number of I/O	38
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	4.75V ~ 5.25V
Data Converters	A/D 3x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	48-BSSOP (0.295", 7.50mm Width)
Supplier Device Package	48-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/rochester-electronics/cy8c22645-12pvxe

Additional System Resources

System Resources, some of which are listed in the previous sections, provide additional capability useful for complete systems. Additional resources include a MAC, low voltage detection, and power on reset. The merits of each system resource are:

- Digital clock dividers provide three customizable clock frequencies for use in applications. The clocks may be routed to both the digital and analog systems. Additional clocks can be generated using digital PSoC blocks as clock dividers.
- Additional digital resources and clocks dedicated to and optimized for CapSense.
- RTC hardware block.
- A multiply accumulate (MAC) provides a fast 8-bit multiplier with 32-bit accumulate, to assist in both general math and digital filters.
- The I^2C module provides 0 to 400 kHz communication over two wires. Slave, master, and multi-master modes are all supported.
- Low voltage detection (LVD) interrupts can signal the application of falling voltage levels, while the advanced power on reset (POR) circuit eliminates the need for a system supervisor.
- An internal voltage reference provides an absolute reference for the analog system, including ADCs and DACs.

PSoC Device Characteristics

Depending on your PSoC device characteristics, the digital and analog systems can have varying numbers of digital and analog blocks. The following table lists the resources available for specific PSoC device groups. The PSoC families covered by this datasheet are highlighted in the table.

Table 1. PSoC Device Characteristics

PSoC Part Number	Digital I/O	Digital Rows	Digital Blocks	Analog Inputs	Analog Outputs	Analog Columns	Analog Blocks	SRAM Size	Flash Size
CY8C29x66 [2]	up to 64	4	16	up to 12	4	4	12	2 K	32 K
CY8C28xxx	up to 44	up to 3	up to 12	up to 44	up to 4	up to 6	up to 12 + 4 [3]	1 K	16 K
CY8C27x43	up to 44	2	8	up to 12	4	4	12	256	16 K
CY8C24x94 [2]	up to 56	1	4	up to 48	2	2	6	1 K	16 K
CY8C24x23A [2]	up to 24	1	4	up to 12	2	2	6	256	4 K
CY8C23x33	up to 26	1	4	up to 12	2	2	4	256	8 K
CY8C22x45 [2]	up to 38	2	8	up to 38	0	4	6 [3]	1 K	16 K
CY8C21x45 [2]	up to 24	1	4	up to 24	0	4	6 [3]	512	8 K
CY8C21x34 [2]	up to 28	1	4	up to 28	0	2	4 [3]	512	8 K
CY8C21x23	up to 16	1	4	up to 8	0	2	4 [3]	256	4 K
CY8C20x34 [2]	up to 28	0	0	up to 28	0	0	3 [3, 4]	512	8 K
CY8C20xx6	up to 36	0	0	up to 36	0	0	3 [3, 4]	up to 2 K	up to 32 K

Notes
2. Automotive qualified devices available in this group.
3. Limited analog functionality.
4. Two analog blocks and one CapSense® block.

Getting Started

For in depth information, along with detailed programming details, see the *PSoC® Technical Reference Manual*.

For up-to-date ordering, packaging, and electrical specification information, see the latest PSoC device datasheets on the web.

Application Notes

Cypress application notes are an excellent introduction to the wide variety of possible PSoC designs.

Development Kits

PSoC Development Kits are available online from and through a growing number of regional and global distributors, which include Arrow, Avnet, Digi-Key, Farnell, Future Electronics, and Newark.

Training

Free PSoC technical training (on demand, webinars, and workshops), which is available online via www.cypress.com, covers a wide variety of topics and skill levels to assist you in your designs.

CYPros Consultants

Certified PSoC consultants offer everything from technical assistance to completed PSoC designs. To contact or become a PSoC consultant go to the CYPros Consultants web site.

Solutions Library

Visit our growing library of solution focused designs. Here you can find various application designs that include firmware and hardware design files that enable you to complete your designs quickly.

Technical Support

Technical support – including a searchable Knowledge Base articles and technical forums – is also available online. If you cannot find an answer to your question, call our Technical Support hotline at 1-800-541-4736.

Development Tools

PSoC Designer™ is the revolutionary Integrated Design Environment (IDE) that you can use to customize PSoC to meet your specific application requirements. PSoC Designer software accelerates system design and time to market. Develop your applications using a library of precharacterized analog and digital peripherals (called user modules) in a drag-and-drop design environment. Then, customize your design by leveraging the dynamically generated application programming interface (API) libraries of code. Finally, debug and test your designs with the integrated debug environment, including in-circuit emulation and standard software debug features. PSoC Designer includes:

- Application editor graphical user interface (GUI) for device and user module configuration and dynamic reconfiguration
- Extensive user module catalog
- Integrated source-code editor (C and assembly)
- Free C compiler with no size restrictions or time limits
- Built-in debugger
- In-circuit emulation
- Built-in support for communication interfaces:
  - Hardware and software I^2C slaves and masters
  - Full-speed USB 2.0
  - Up to four full-duplex universal asynchronous receiver/transmitters (UARTs), SPI master and slave, and wireless

PSoC Designer supports the entire library of PSoC 1 devices and runs on Windows XP, Windows Vista, and Windows 7.

PSoC Designer Software Subsystems

Design Entry

In the chip-level view, choose a base device to work with. Then select different onboard analog and digital components that use the PSoC blocks, which are called user modules. Examples of user modules are analog-to-digital converters (ADCs), digital-to-analog converters (DACs), amplifiers, and filters. Configure the user modules for your chosen application and connect them to each other and to the proper pins. Then generate your project. This prepopulates your project with APIs and libraries that you can use to program your application.

The tool also supports easy development of multiple configurations and dynamic reconfiguration. Dynamic reconfiguration makes it possible to change configurations at run time. In essence, this allows you to use more than 100 percent of PSoC's resources for a given application.

Code Generation Tools

The code generation tools work seamlessly within the PSoC Designer interface and have been tested with a full range of debugging tools. You can develop your design in C, assembly, or a combination of the two.

Assemblers. The assemblers allow you to merge assembly code seamlessly with C code. Link libraries automatically use absolute addressing or are compiled in relative mode, and linked with other software modules to get absolute addressing.

Table 3. 48-pin Part Pinout (SSOP) (continued)

Pin No.	Type		Pin Name	Description
	Digital	Analog		
43	I/O	I, MR	P2[6]	Direct input to analog block
44	I/O	I, MR	P0[0]	Analog column mux input
45	I/O	I, MR	P0[2]	Analog column mux input
46	I/O	I, MR	P0[4]	Analog column mux input
47	I/O	I, MR	P0[6]	Analog column mux input
48	Power		V_{DD}	Supply voltage

LEGEND: A = Analog, I = Input, O = Output, MR= Right analog mux bus input, ML= Left analog mux bus input

Registers

This section lists the registers of this PSoC device family by mapping tables. For detailed register information, refer to the PSoC Technical Reference Manual for CY8C21x45 and CY8C22x45 devices.

Register Conventions

The register conventions specific to this section are listed in the following table.

Table 4. Abbreviations

Convention	Description
RW	Read and write register or bit(s)
R	Read register or bit(s)
W	Write register or bit(s)
L	Logical register or bit(s)
C	Clearable register or bit(s)
#	Access is bit specific

Register Mapping Tables

The PSoC device has a total register address space of 512 bytes. The register space is referred to as I/O space and is divided into two banks. The XIO bit in the Flag register (CPU_F) determines which bank the user is currently in. When the XIO bit is set the user is in Bank 1.

Note In the following register mapping tables, blank fields are Reserved and must not be accessed.

Absolute Maximum Ratings

Exceeding maximum ratings may shorten the useful life of the device. User guidelines are not tested.

Table 7. Absolute Maximum Ratings

Symbol	Description	Min	Typ	Max	Units	Notes
T_{STG}	Storage temperature	–55	25	+150	°C	Higher storage temperatures reduce data retention time. Recommended storage temperature is +25 °C ±25 °C. Time spent in storage at a temperature greater than 65 °C counts toward the $Flash_{DR}$ electrical specification in Table 16 on page 20.
$T_{BAKETEMP}$	Bake temperature	–	125	See package label	°C	
$t_{BAKETIME}$	Bake time	See package label	–	72	Hours	
T_A	Ambient temperature with power applied A-grade devices E-grade devices	 –40 –40	 – –	 +85 +125	 °C °C	
V_{DD}	Supply voltage on V_{DD} relative to V_{SS}	–0.5	–	+6.0	V	
V_{IO}	DC input voltage	V_{SS} – 0.5	–	V_{DD} + 0.5	V	
V_{IOz}	DC voltage applied to tristate	V_{SS} – 0.5	–	V_{DD} + 0.5	V	
I_{MIO}	Maximum current into any port pin	–25	–	+50	mA	
ESD	Electrostatic discharge voltage	2000	–	–	V	Human body model ESD
LU	Latch up current	–	–	200	mA	

Operating Temperature

Table 8. Operating Temperature

Symbol	Description	Min	Typ	Max	Units	Notes
T_A	Ambient temperature A-grade devices E-grade devices	 –40 –40	 – –	 +85 +125	 °C °C	
T_J	Junction temperature A-grade devices E-grade devices	 –40 –40	 – –	 +100 +135	 °C °C	The temperature rise from ambient to junction is package specific. See Table 27 on page 34. The user must limit the power consumption to comply with this requirement.

Electrical Specifications

This section presents the DC and AC electrical specifications for automotive CY8C21x45 and CY8C22x45 PSoC devices. For the latest electrical specifications, check the most recent data sheet by visiting the web at http://www.cypress.com.

Specifications are valid for A-grade devices at –40 °C ≤ T_A ≤ 85 °C, T_J ≤ 100 °C, and for E-grade devices at –40 °C ≤ T_A ≤ 125 °C, T_J ≤ 135 °C, unless noted otherwise.

Figure 5. Voltage vs. CPU Frequency for A-grade Devices

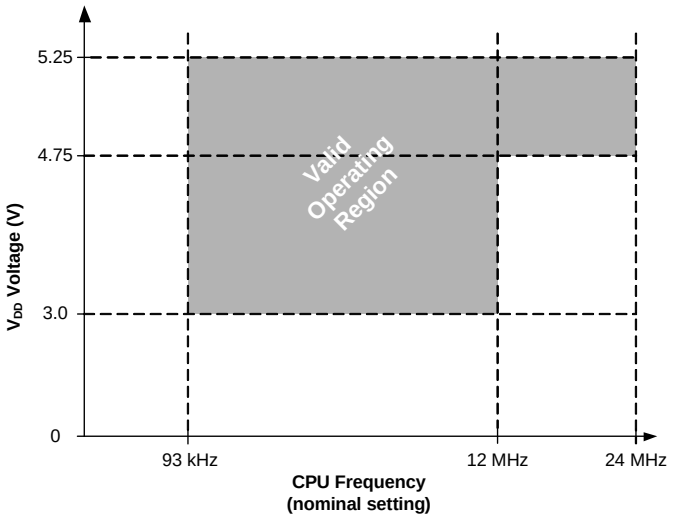


Figure 6. Voltage vs. CPU Frequency for E-grade Devices

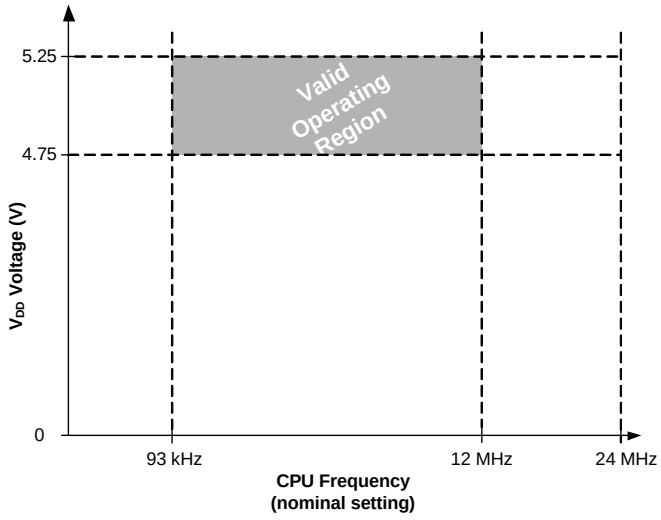
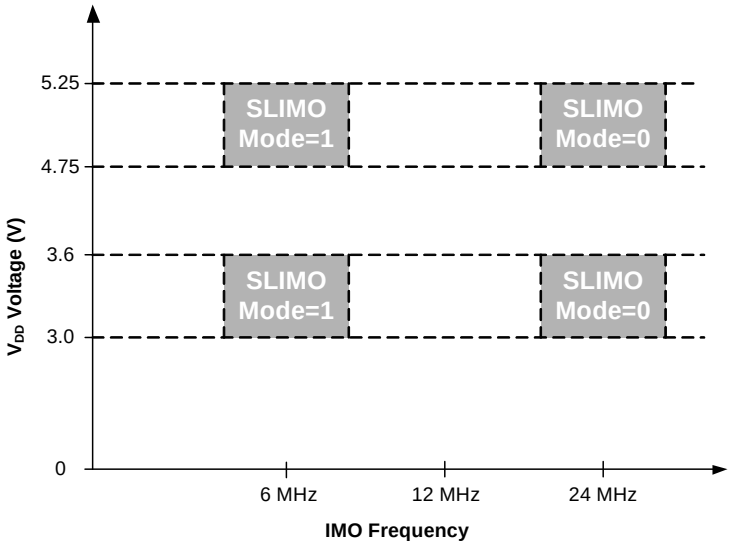


Figure 7. IMO Frequency Trim Options (A-grade Devices Only)



DC Electrical Characteristics

DC Chip Level Specifications

Table 9 lists the guaranteed maximum and minimum specifications for automotive A-grade and E-grade devices. Unless otherwise noted, all specifications in the table apply to A-grade devices for the voltage and temperature ranges of: 4.75 V to 5.25 V and –40 °C to 85 °C, or 3.0 V to 3.6 V and –40 °C to 85 °C. Unless otherwise noted, all specifications in the table also apply to E-grade devices for the voltage and temperature ranges of: 4.75 V to 5.25 V and –40 °C to 125 °C. Typical parameters apply to 5 V and 3.3 V at 25 °C, unless specified otherwise, and are for design guidance only.

Table 9. DC Chip Level Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
V_{DD}	Supply voltage A-grade devices E-grade devices	 3.0 4.75	 – –	 5.25 5.25	 V V	See Table 15 on page 19
I_{DD}	Supply current A-grade devices, 3.0 V ≤ V_{DD} ≤ 3.6 V A-grade devices, 4.75 V ≤ V_{DD} ≤ 5.25 V E-grade devices	 – – –	 4 7 8	 7 12 15	 mA mA mA	CPU = 3 MHz, 48 MHz disabled. VC1 = 1.5 MHz, VC2 = 93.75 kHz, VC3 = 93.75 kHz, Analog blocks disabled
I_{SB}	Sleep (mode) current A-grade devices, 3.0 V ≤ V_{DD} ≤ 3.6 V A-grade devices, 4.75 V ≤ V_{DD} ≤ 5.25 V E-grade devices	 – – –	 3 4 4	 12 25 25	 µA µA µA	Everything disabled except ILO, POR, LVD, Sleep Timer, and WDT circuits
I_{SBXTL}	Sleep (mode) current with ECO A-grade devices, 3.0 V ≤ V_{DD} ≤ 3.6 V A-grade devices, 4.75 V ≤ V_{DD} ≤ 5.25 V E-grade devices	 – – –	 4 5 5	 13 26 26	 µA µA µA	Everything disabled except ECO, POR, LVD, Sleep Timer, and WDT circuits
V_{REF}	Reference voltage (Bandgap)	1.275	1.30	1.325	V	Trimmed for appropriate V_{DD} setting.

DC GPIO Specifications

Table 10 lists the guaranteed maximum and minimum specifications for automotive A-grade and E-grade devices. Unless otherwise noted, all specifications in the table apply to A-grade devices for the voltage and temperature ranges of: 4.75 V to 5.25 V and –40 °C to 85 °C, or 3.0 V to 3.6 V and –40 °C to 85 °C. Unless otherwise noted, all specifications in the table also apply to E-grade devices for the voltage and temperature ranges of: 4.75 V to 5.25 V and –40 °C to 125 °C. Typical parameters apply to 5 V and 3.3 V at 25 °C, unless specified otherwise, and are for design guidance only.

Table 10. DC GPIO Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
R_{PU}	Pull-up resistor	4	5.6	8	kΩ	
R_{PD}	Pull-down resistor	4	5.6	8	kΩ	Also applies to the internal pull-down resistor on the XRES pin
V_{OH}	High output level	V_{DD} – 1.0	–	–	V	I_{OH} = 10 mA, V_{DD} = 4.75 to 5.25 V (80 mA maximum combined I_{OH} budget)
V_{OL}	Low output level	–	–	0.75	V	I_{OL} = 25 mA, V_{DD} = 4.75 to 5.25 V (100 mA maximum combined I_{OL} budget)
		–	–	0.65	V	I_{OL} = 5 mA, V_{DD} = 3.0 to 3.6 V
I_{OH}	High-level source current	10	–	–	mA	$V_{OH} \geq V_{DD}$ – 1.0 V, see the limitations of the total current in the note for V_{OH}.
I_{OL}	Low-level sink current	25	–	–	mA	$V_{OL} \leq 0.75$ V, see the limitations of the total current in the note for V_{OL}.
V_{IL}	Input low level	–	–	0.8	V	
V_{IH}	Input high level	2.1	–		V	
V_H	Input hysteresis	–	60	–	mV	
I_{IL}	Input leakage (absolute value)	–	1	–	nA	Gross tested to 1 μA
C_{IN}	Capacitive load on pins as input	–	3.5	10	pF	Package and pin dependent. T_A = 25 °C
C_{OUT}	Capacitive load on pins as output	–	3.5	10	pF	Package and pin dependent. T_A = 25 °C

AC Electrical Characteristics

AC Chip Level Specifications

The following tables list the guaranteed maximum and minimum specifications for automotive A-grade and E-grade devices. Unless otherwise noted, all specifications in the table apply to A-grade devices for the voltage and temperature ranges of: 4.75 V to 5.25 V and –40 °C to 85 °C, or 3.0 V to 3.6 V and –40 °C to 85 °C. Unless otherwise noted, all specifications in the table also apply to E-grade devices for the voltage and temperature ranges of: 4.75 V to 5.25 V and –40 °C to 125 °C. Typical parameters apply to 5 V and 3.3 V at 25 °C, unless specified otherwise, and are for design guidance only.

Table 17. AC Chip-Level Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
F_{IMO24}	Internal main oscillator frequency for 24 MHz A-grade devices, 4.75 V ≤ V_{DD} ≤ 5.25 V A-grade devices, 3.0 V ≤ V_{DD} ≤ 3.6 V E-grade devices	 22.8 22.5 22.3	 24 24 24	 25.2 [11] 25.5 [11] 25.7 [11]	 MHz MHz MHz	Trimmed for 5 V or 3.3 V operation using factory trim values. See Figure 7 on page 14.
F_{IMO6}	Internal main oscillator frequency for 6 MHz A-grade devices E-grade devices	 5.5 5.5	 6 6	 6.5 [11] 6.5 [11]	 MHz MHz	Trimmed for 5 V or 3.3 V operation using factory trim values. See Figure 7 on page 14.
F_{CPU1}	CPU frequency (5 V V_{DD} operation) A-grade devices E-grade devices	 0.089 0.089	 – –	 25.2 [11] 12.6 [11]	 MHz MHz	SLIMO mode = 0.
F_{CPU2}	CPU frequency (3.3 V V_{DD} operation)	0.089	–	12.6 [11]	MHz	A-grade devices only. SLIMO mode = 0.
F_{BLK5}	Digital PSoC block frequency (5 V V_{DD} operation) A-grade devices E-grade devices	 0 0	 48 24	 50.4 [11, 12] 25.2 [11, 12]	 MHz MHz	Refer to Table 20 on page 24.
F_{BLK33}	Digital PSoC block frequency (3.3 V V_{DD} operation)	0	24	24.6 [11]	MHz	A-grade devices only
F_{32K1}	ILO frequency	15	32	75	kHz	This specification applies when the ILO has been trimmed.
F_{32KU}	ILO untrimmed frequency	5	–	100	kHz	After a reset and before the M8C processor starts to execute, the ILO is not trimmed.
t_{XRST}	External reset pulse width	10	–	–	µs	
DC24M	24 MHz duty cycle	40	50	60	%	
DC_{ILO}	ILO duty cycle	20	50	80	%	
Fout48M	48 MHz output frequency	45.6	48.0	50.4 [11]	MHz	
F_{MAX}	Maximum frequency of signal on row input or row output	–	–	12.6	MHz	
$SR_{POWERUP}$	Power supply slew rate	–	–	250	V/ms	V_{DD} slew rate during power-up.
$t_{POWERUP}$	Time between end of POR state and CPU code execution	–	16	100	ms	Power-up from 0 V.

Notes
11. Accuracy derived from IMO with appropriate trim for V_{DD} range
12. Refer to the individual user module data sheets for information on maximum frequencies for user modules.

AC Digital Block Specifications

The following tables list the guaranteed maximum and minimum specifications for automotive A-grade and E-grade devices. Unless otherwise noted, all specifications in the table apply to A-grade devices for the voltage and temperature ranges of: 4.75 V to 5.25 V and –40 °C to 85 °C, or 3.0 V to 3.6 V and –40 °C to 85 °C. Unless otherwise noted, all specifications in the table also apply to E-grade devices for the voltage and temperature ranges of: 4.75 V to 5.25 V and –40 °C to 125 °C. Typical parameters apply to 5 V and 3.3 V at 25 °C, unless specified otherwise, and are for design guidance only.

Table 20. AC Digital Block Specifications

Function	Description	Min	Typ	Max	Units	Notes
All functions	Block Input Clock Frequency					
	$V_{DD} \geq 4.75$ V	–	–	50.4 [15]	MHz	
	$V_{DD} < 4.75$ V	–	–	25.2 [15]	MHz	
Timer	Input Clock Frequency					
	No Capture, $V_{DD} \geq 4.75$ V	–	–	50.4 [15]	MHz	
	No Capture, $V_{DD} < 4.75$ V	–	–	25.2 [15]	MHz	
	With Capture	–	–	25.2 [15]	MHz	
	Capture Pulse Width	50 [14]	–	–	ns	
Counter	Input Clock Frequency					
	No Enable Input, $V_{DD} \geq 4.75$ V	–	–	50.4 [15]	MHz	
	No Enable Input, $V_{DD} < 4.75$ V	–	–	25.2 [15]	MHz	
	With Enable Input	–	–	25.2 [15]	MHz	
	Enable Input Pulse Width	50 [14]	–	–	ns	
Dead Band	Kill Pulse Width					
	Asynchronous Restart Mode	20	–	–	ns	
	Synchronous Restart Mode	50 [14]	–	–	ns	
	Disable Mode	50 [14]	–	–	ns	
	Input Clock Frequency					
	$V_{DD} \geq 4.75$ V	–	–	50.4 [15]	MHz	
	$V_{DD} < 4.75$ V	–	–	25.2 [15]	MHz	
CRCPRS (PRS Mode)	Input Clock Frequency					
	$V_{DD} \geq 4.75$ V	–	–	50.4 [15]	MHz	
	$V_{DD} < 4.75$ V	–	–	25.2 [15]	MHz	
CRCPRS (CRC Mode)	Input Clock Frequency	–	–	25.2 [15]	MHz	
SPIM	Input Clock Frequency	–	–	8.4 [15]	MHz	The SPI serial clock (SCLK) frequency is equal to the input clock frequency divided by 2.
SPIS	Input Clock (SCLK) Frequency	–	–	4.2 [15]	MHz	The input clock is the SPI SCLK in SPIS mode.
	Width of SS_Negated Between Transmissions	50 [14]	–	–	ns	

Note
14. 50 ns minimum input pulse width is based on the input synchronizers running at 24 MHz (42 ns nominal period).

AC External Clock Specifications

The following tables list the guaranteed maximum and minimum specifications for automotive A-grade and E-grade devices. Unless otherwise noted, all specifications in the table apply to A-grade devices for the voltage and temperature ranges of: 4.75 V to 5.25 V and –40 °C to 85 °C, or 3.0 V to 3.6 V and –40 °C to 85 °C. Unless otherwise noted, all specifications in the table also apply to E-grade devices for the voltage and temperature ranges of: 4.75 V to 5.25 V and –40 °C to 125 °C. Typical parameters apply to 5 V and 3.3 V at 25 °C, unless specified otherwise, and are for design guidance only.

Table 21. AC External Clock Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
F_{OSCEXT}	Frequency	0.093	–	24.6	MHz	
–	High period	20.0	–	5300	ns	
–	Low period	20.0	–	–	ns	
–	Power-up IMO to switch	150	–	–	µs	

AC SAR10 ADC Specifications

Table 22 lists the guaranteed maximum and minimum specifications for automotive A-grade and E-grade devices. Unless otherwise noted, all specifications in the table apply to A-grade devices for the voltage and temperature ranges of: 4.75 V to 5.25 V and –40 °C to 85 °C, or 3.0 V to 3.6 V and –40 °C to 85 °C. Unless otherwise noted, all specifications in the table also apply to E-grade devices for the voltage and temperature ranges of: 4.75 V to 5.25 V and –40 °C to 125 °C. Typical parameters apply to 5 V and 3.3 V at 25 °C, unless specified otherwise, and are for design guidance only.

Table 22. AC SAR10 ADC Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
F_{INADC}	SAR ADC input clock frequency	–	–	2	MHz	The sample rate of the SAR10 ADC is equal to F_{INADC} divided by 13.

Development Tool Selection

This section presents the development tools available for the automotive CY8C21x45 and CY8C22x45 families.

Software

PSoC Designer

At the core of the PSoC development software suite is PSoC Designer. Utilized by thousands of PSoC developers, this robust software has been facilitating PSoC designs for years. PSoC Designer is available free of charge at http://www.cypress.com. PSoC Designer comes with a free C compiler.

PSoC Programmer

Flexible enough to be used on the bench in development, yet suitable for factory programming, PSoC Programmer works either as a standalone programming application or it can operate directly from PSoC Designer. PSoC Programmer software is compatible with both PSoC ICE-Cube In-Circuit Emulator and PSoC MiniProg. PSoC programmer is available free of charge at http://www.cypress.com.

Development Kits

All development kits can be purchased from the Cypress Online Store. The online store also has the most up to date information on kit contents, descriptions, and availability.

CY3215-DK Basic Development Kit

The CY3215-DK is for prototyping and development with PSoC Designer. This kit supports in-circuit emulation and the software interface allows users to run, halt, and single step the processor and view the contents of specific memory locations. Advanced emulation features are also supported through PSoC Designer. The kit includes:

- ICE-Cube unit
- 28-pin PDIP emulation pod for CY8C29466-24PXI
- 28-pin CY8C29466-24PXI PDIP PSoC device samples (two)
- PSoC Designer software CD
- ISSP cable
- MiniEval socket programming and evaluation board
- Backward compatibility cable (for connecting to legacy pods)
- Universal 110/220 power supply (12 V)
- European plug adapter
- USB 2.0 cable
- Getting Started guide
- Development kit registration form

CY3280-22X45 Universal CapSense Controller Board

The CY3280-22X45 controller board is an additional controller board for the CY3280-BK1 Universal CapSense Controller Kit. The Universal CapSense Controller kit is designed for easy prototyping and debug of CapSense designs with pre-defined control circuitry and plug-in hardware. The CY3280-22X45 kit contains no plug-in hardware. Therefore, it is only usable if plug-in hardware is purchased as part of the CY3280-BK1 kit or other separate kits. The kit includes:

- CY3280-22X45 universal CapSense controller board
- CY3280-22X45 universal CapSense controller board CD
- DC power supply
- Printed documentation

CY3280-CPM1 CapSensePlus Module

The CY3280-CPM1 CapSensePlus Module is a plug-in module board for the CY3280-22X45 CapSense controller board kit. This plug-in module has no capacitive sensors on it. Instead, it has other general circuitry (such as a seven-segment display, potentiometer, LEDs, buttons, thermistor) that can be used to develop applications that require capacitive sensing along with other additional functionality. To use this kit, a CY3280-22X45 kit is required.

Evaluation Tools

All evaluation tools can be purchased from the Cypress online store. The online store also has the most up-to-date information on kit contents, descriptions, and availability.

CY3210-PSoCEval1

The CY3210-PSoCEval1 kit features an evaluation board and the MiniProg1 programming unit. The evaluation board includes an LCD module, potentiometer, LEDs, an RS-232 port, and plenty of breadboarding space to meet all of your evaluation needs. The kit includes:

- Evaluation board with LCD module
- MiniProg programming unit
- 28-pin CY8C29466-24PXI PDIP PSoC device sample (two)
- PSoC Designer software CD
- Getting Started guide
- USB 2.0 cable

Device Programmers

All device programmers can be purchased from the Cypress Online Store.

CY3210-MiniProg1

The CY3210-MiniProg1 kit allows the user to program PSoC devices through the MiniProg1 programming unit. The MiniProg is a small, compact prototyping programmer that connects to the PC through a provided USB 2.0 cable. The kit includes:

- MiniProg programming unit
- MiniEval socket programming and evaluation board
- 28-pin CY8C29466-24PXI PDIP PSoC device sample
- PSoC Designer software CD
- Getting Started guide
- USB 2.0 cable

CY3207ISSP In-System Serial Programmer

The CY3207ISSP is a production programmer. It includes protection circuitry and an industrial case that is more robust than the MiniProg in a production-programming environment.

Note CY3207ISSP needs special software and is not compatible with PSoC Programmer. This software is free and can be downloaded from http://www.cypress.com. The kit includes:

- CY3207 programmer unit
- PSoC ISSP software CD
- 110 ~ 240-V power supply, Euro-Plug adapter
- USB 2.0 cable

Accessories (Emulation and Programming)

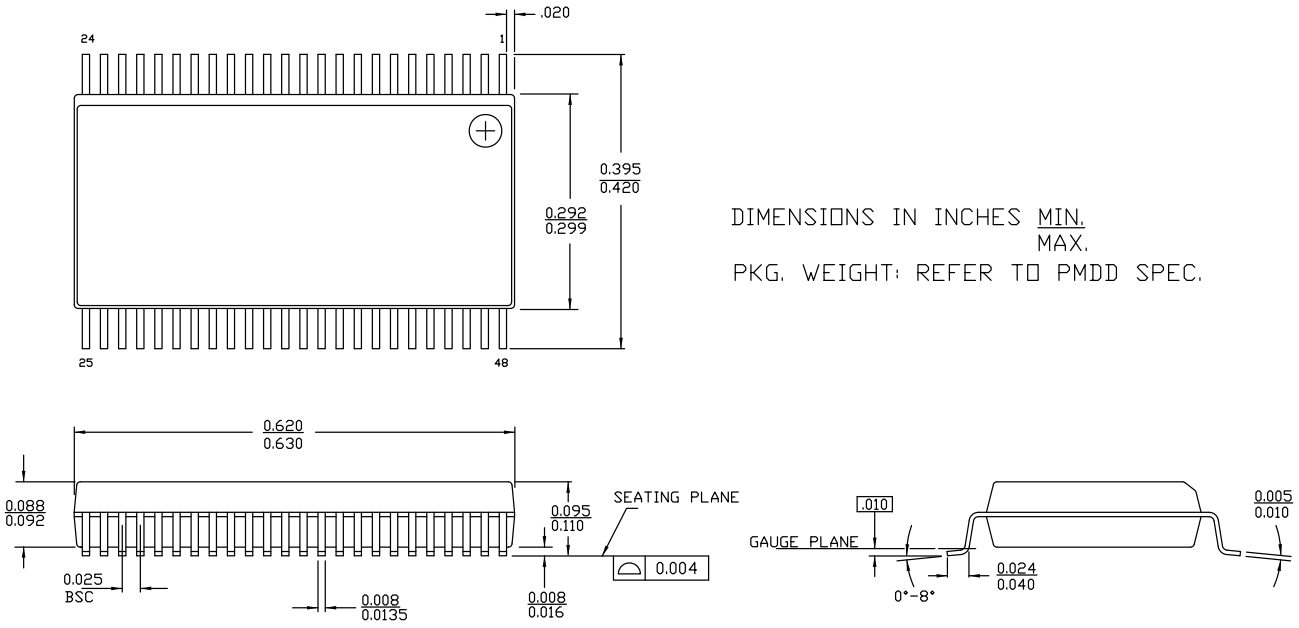
Table 25. Emulation and Programming Accessories

Part Number	Pin Package	Pod Kit [19]	Foot Kit [20]	Prototyping Module	Adapter [21]
CY8C21345-24PVXA CY8C21345-12PVXE CY8C22345-24PVXA CY8C22345H-24PVXA CY8C22345-12PVXE	28-pin SSOP	CY3250-22345	CY3250-28SSOP-FK	–	AS-28-28-02SS-6ENP-GANG
CY8C21645-24PVXA CY8C21645-12PVXE CY8C22645-24PVXA CY8C22645-12PVXE	48-pin SSOP	–	–	–	AS-48-48-01SS-6-GANG

Notes
19. Pod kit contains an emulation pod, a flex-cable (connects the pod to the ICE), two feet, and device samples.
20. Foot kit includes surface mount feet that can be soldered to the target PCB.
21. Programming adapter converts non-DIP package to DIP footprint. Specific details and ordering information for each of the adapters can be found at http://www.emulation.com.

Packaging Information (continued)

Figure 11. 48-pin SSOP (300 Mils) Package Outline, 51-85061



Thermal Impedances

Table 27. Thermal Impedances per Package

Package	Typical θ_{JA} [22]
28-pin SSOP	97.6 °C/W
48-pin SSOP	69 °C/W

Capacitance on Crystal Pins

Table 28. Typical Package Capacitance on Crystal Pins

Package	Package Capacitance
28-pin SSOP	2.8 pF
48-pin SSOP	3.3 pF

Solder Reflow Specifications

Table 29 shows the solder reflow temperature limits that must not be exceeded.

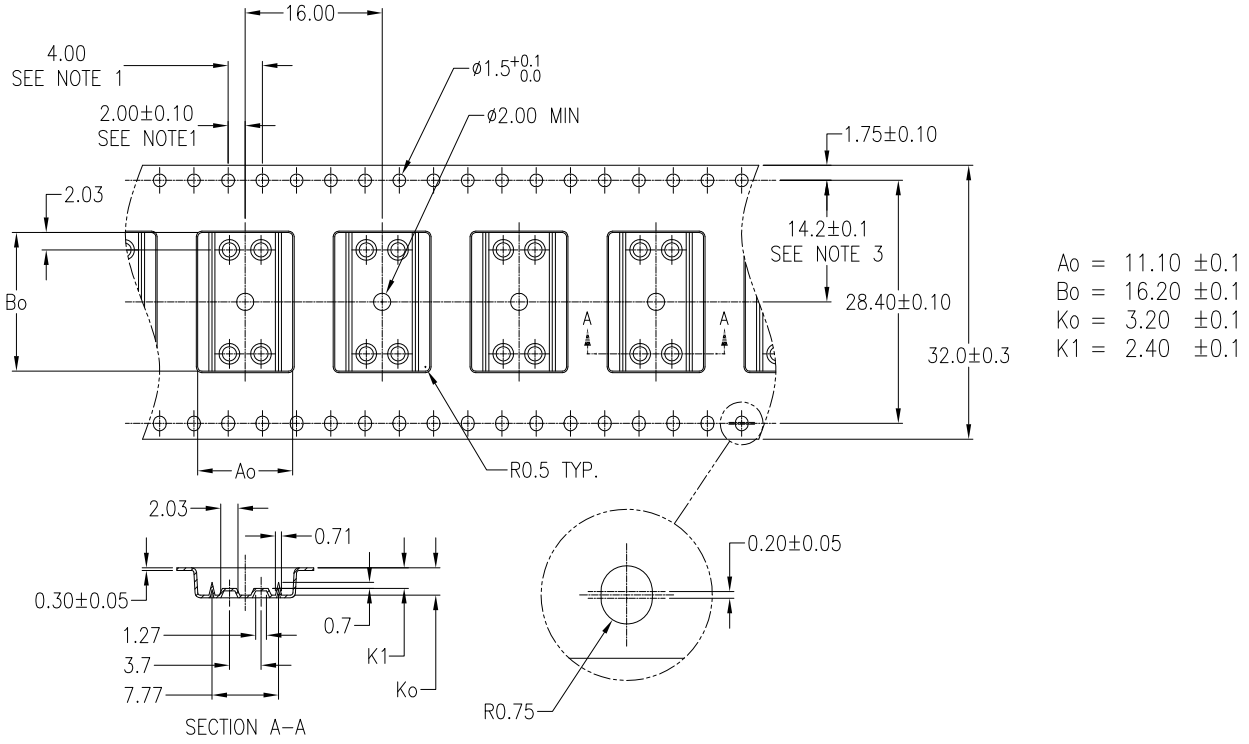
Table 29. Solder Reflow Specifications

Package	Maximum Peak Temperature (T_C)	Maximum Time above T_C – 5 °C
28-pin SSOP	260 °C	30 seconds
48-pin SSOP	260 °C	30 seconds

Note
22. $T_J = T_A + POWER \times \theta_{JA}$

Figure 13. 48-pin SSOP (300 Mils) Carrier Tape, 51-51104

NOTES:
1. 10 SPROCKET HOLE PITCH CUMULATIVE TOLERANCE ±0.2
2. CAMBER IN COMPLIANCE WITH EIA 481
3. POCKET POSITION RELATIVE TO SPROCKET HOLE MEASURED AS TRUE POSITION OF POCKET, NOT POCKET HOLE



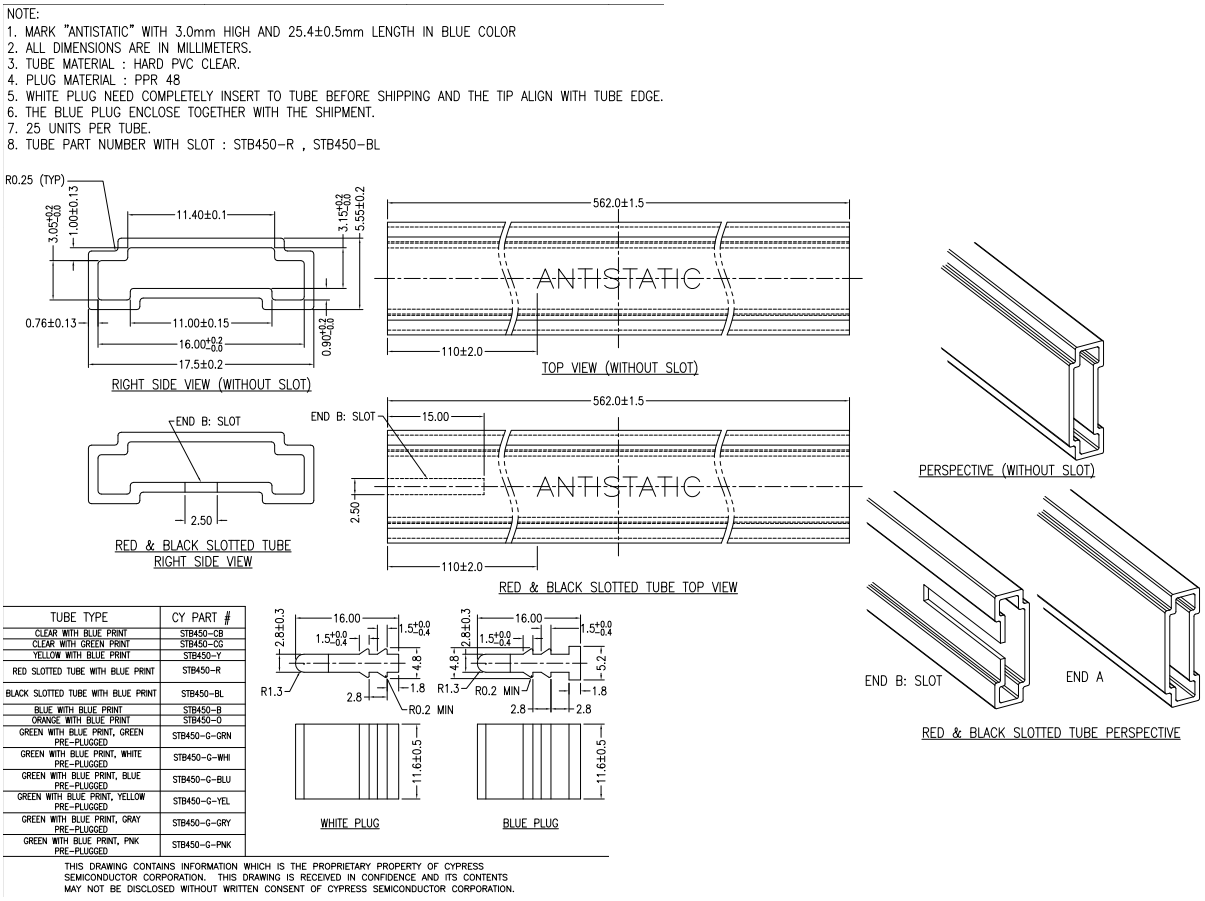
51-51104 *E

Table 30. Tape and Reel Specifications

Package	Cover Tape Width (mm)	Hub Size (inches)	Minimum Leading Empty Pockets	Minimum Trailing Empty Pockets	Standard Full Reel Quantity
28-pin SSOP	13.3	7	42	25	1000
48-pin SSOP	25.5	4	32	19	1000

Tube Information

Figure 14. 28-pin SSOP, 32-pin SOIC (450 Mils Body) Shipping Tube, 51-51029



TUBE TYPE	CY PART #
CLEAR WITH BLUE PRINT	STB450-CB
CLEAR WITH GREEN PRINT	STB450-CG
YELLOW WITH BLUE PRINT	STB450-Y
RED SLOTTED TUBE WITH BLUE PRINT	STB450-R
BLACK SLOTTED TUBE WITH BLUE PRINT	STB450-BL
BLUE WITH BLUE PRINT	STB450-B
ORANGE WITH BLUE PRINT	STB450-O
GREEN WITH BLUE PRINT, GREEN PRE-PLUGGED	STB450-G-GRN
GREEN WITH BLUE PRINT, WHITE PRE-PLUGGED	STB450-G-WHI
GREEN WITH BLUE PRINT, BLUE PRE-PLUGGED	STB450-G-BLU
GREEN WITH BLUE PRINT, YELLOW PRE-PLUGGED	STB450-G-YEL
GREEN WITH BLUE PRINT, GRAY PRE-PLUGGED	STB450-G-GRY
GREEN WITH BLUE PRINT, PNK PRE-PLUGGED	STB450-G-PNK

51-51029 *E

Document Conventions

Units of Measure

Table 32 lists the units of measure that are used in this document.

Table 32. Units of Measure

Symbol	Unit of Measure	Symbol	Unit of Measure
kB	1024 bytes	ms	millisecond
°C	degree Celsius	mV	millivolt
kHz	kilohertz	nA	nanoampere
kΩ	kilohm	ns	nanosecond
LSbit	least-significant bit	W	ohm
MHz	megahertz	%	percent
µA	microampere	pF	picofarad
µs	microsecond	ps	picosecond
µV	microvolt	pA	picoampere
mA	milliampere	V	volt
mm	millimeter	W	watt

Numeric Conventions

Hexadecimal numbers are represented with all letters in uppercase with an appended lowercase ‘h’ (for example, ‘14h’ or ‘3Ah’). Hexadecimal numbers may also be represented by a ‘0x’ prefix, the C coding convention. Binary numbers have an appended lowercase ‘b’ (for example, 01010100b’ or ‘01000011b’). Numbers not indicated by an ‘h’ or ‘b’ are decimals.

Glossary

active high	1. A logic signal having its asserted state as the logic 1 state. 2. A logic signal having the logic 1 state as the higher voltage of the two states.
analog blocks	The basic programmable opamp circuits. These are SC (switched capacitor) and CT (continuous time) blocks. These blocks can be interconnected to provide ADCs, DACs, multi-pole filters, gain stages, and much more.
analog-to-digital (ADC)	A device that changes an analog signal to a digital signal of corresponding magnitude. Typically, an ADC converts a voltage to a digital number. The digital-to-analog (DAC) converter performs the reverse operation.
API (Application Programming Interface)	A series of software routines that comprise an interface between a computer application and lower level services and functions (for example, user modules and libraries). APIs serve as building blocks for programmers that create software applications.
asynchronous	A signal whose data is acknowledged or acted upon immediately, irrespective of any clock signal.
bandgap reference	A stable voltage reference design that matches the positive temperature coefficient of VT with the negative temperature coefficient of VBE, to produce a zero temperature coefficient (ideally) reference.
bandwidth	1. The frequency range of a message or information processing system measured in hertz. 2. The width of the spectral region over which an amplifier (or absorber) has substantial gain (or loss); it is sometimes represented more specifically as, for example, full width at half maximum.
bias	1. A systematic deviation of a value from a reference value. 2. The amount by which the average of a set of values departs from a reference value. 3. The electrical, mechanical, magnetic, or other force (field) applied to a device to establish a reference level to operate the device.

Glossary (continued)

external reset (XRES)	An active high signal that is driven into the PSoC device. It causes all operation of the CPU and blocks to stop and return to a pre-defined state.
flash	An electrically programmable and erasable, non-volatile technology that provides users with the programmability and data storage of EPROMs, plus in-system erasability. Non-volatile means that the data is retained when power is off.
Flash block	The smallest amount of Flash ROM space that may be programmed at one time and the smallest amount of Flash space that may be protected. A Flash block holds 64 bytes.
frequency	The number of cycles or events per unit of time, for a periodic function.
gain	The ratio of output current, voltage, or power to input current, voltage, or power, respectively. Gain is usually expressed in dB.
I^2C	A two-wire serial computer bus by Philips Semiconductors (now NXP Semiconductors). I2C is an Inter-Integrated Circuit. It is used to connect low-speed peripherals in an embedded system. The original system was created in the early 1980s as a battery control interface, but it was later used as a simple internal bus system for building control electronics. I2C uses only two bi-directional pins, clock and data, both running at +5V and pulled high with resistors. The bus operates at 100 kbits/second in standard mode and 400 kbits/second in fast mode.
ICE	The in-circuit emulator that allows users to test the project in a hardware environment, while viewing the debugging device activity in a software environment (PSoC Designer).
input/output (I/O)	A device that introduces data into or extracts data from a system.
interrupt	A suspension of a process, such as the execution of a computer program, caused by an event external to that process, and performed in such a way that the process can be resumed.
interrupt service routine (ISR)	A block of code that normal code execution is diverted to when the M8C receives a hardware interrupt. Many interrupt sources may each exist with its own priority and individual ISR code block. Each ISR code block ends with the RETI instruction, returning the device to the point in the program where it left normal program execution.
jitter	1. A misplacement of the timing of a transition from its ideal position. A typical form of corruption that occurs on serial data streams. 2. The abrupt and unwanted variations of one or more signal characteristics, such as the interval between successive pulses, the amplitude of successive cycles, or the frequency or phase of successive cycles.
low-voltage detect (LVD)	A circuit that senses V_{DD} and provides an interrupt to the system when V_{DD} falls below a selected threshold.
M8C	An 8-bit Harvard-architecture microprocessor. The microprocessor coordinates all activity inside a PSoC by interfacing to the Flash, SRAM, and register space.
master device	A device that controls the timing for data exchanges between two devices. Or when devices are cascaded in width, the master device is the one that controls the timing for data exchanges between the cascaded devices and an external interface. The controlled device is called the ***slave device***.
microcontroller	An integrated circuit chip that is designed primarily for control systems and products. In addition to a CPU, a microcontroller typically includes memory, timing circuits, and IO circuitry. The reason for this is to permit the realization of a controller with a minimal quantity of chips, thus achieving maximal possible miniaturization. This in turn, reduces the volume and the cost of the controller. The microcontroller is normally not used for general-purpose computation as is a microprocessor.
mixed-signal	The reference to a circuit containing both analog and digital techniques and components.

Glossary (continued)

modulator	A device that imposes a signal on a carrier.
noise	1. A disturbance that affects a signal and that may distort the information carried by the signal. 2. The random variations of one or more characteristics of any entity such as voltage, current, or data.
oscillator	A circuit that may be crystal controlled and is used to generate a clock frequency.
parity	A technique for testing transmitting data. Typically, a binary digit is added to the data to make the sum of all the digits of the binary data either always even (even parity) or always odd (odd parity).
phase-locked loop (PLL)	An electronic circuit that controls an ***oscillator*** so that it maintains a constant phase angle relative to a reference signal.
pinouts	The pin number assignment: the relation between the logical inputs and outputs of the PSoC device and their physical counterparts in the printed circuit board (PCB) package. Pinouts involve pin numbers as a link between schematic and PCB design (both being computer generated files) and may also involve pin names.
port	A group of pins, usually eight.
power on reset (POR)	A circuit that forces the PSoC device to reset when the voltage is below a pre-set level. This is one type of hardware reset.
PSoC®	Cypress Semiconductor's PSoC® is a registered trademark and Programmable System-on-Chip™ is a trademark of Cypress.
PSoC Designer™	The software for Cypress' Programmable System-on-Chip technology.
pulse width modulator (PWM)	An output in the form of duty cycle which varies as a function of the applied measurand
RAM	An acronym for random access memory. A data-storage device from which data can be read out and new data can be written in.
register	A storage device with a specific capacity, such as a bit or byte.
reset	A means of bringing a system back to a know state. See hardware reset and software reset.
ROM	An acronym for read only memory. A data-storage device from which data can be read out, but new data cannot be written in.
serial	1. Pertaining to a process in which all events occur one after the other. 2. Pertaining to the sequential or consecutive occurrence of two or more related activities in a single device or channel.
settling time	The time it takes for an output signal or value to stabilize after the input has changed from one value to another.
shift register	A memory storage device that sequentially shifts a word either left or right to output a stream of serial data.
slave device	A device that allows another device to control the timing for data exchanges between two devices. Or when devices are cascaded in width, the slave device is the one that allows another device to control the timing of data exchanges between the cascaded devices and an external interface. The controlling device is called the master device.

Errata

This section describes the errata for the CY8C21x45, CY8C22x45 family of PSoC devices. Details include errata trigger conditions, scope of impact, available workaround, and silicon revision applicability.

Contact your local Cypress Sales Representative if you have questions.

Part Numbers Affected

Part Number	Device Characteristics
CY8C21345	All Variants
CY8C21645	All Variants
CY8C22345	All Variants
CY8C22645	All Variants

CY8C21x45, CY8C22x45 Qualification Status

Product Status: In Production

Errata Summary

The following table defines the errata applicable for this PSoC family device.

Items	Part Number	Silicon Revision	Fix Status
1. Free Running Nonstop Reading cause 7 LSB Pseudo Code Variation in SAR10ADC	All CY8C21x45, CY8C22x45 devices affected	All	Silicon fix not planned. Use workaround.
2. Internal Main Oscillator (IMO) Tolerance Deviation at Temperature Extremes	All CY8C21x45, CY8C22x45 devices affected	All	Silicon fix not planned. Use workaround.

1. Free Running Nonstop Reading cause 7 LSB Pseudo Code Variation in SAR10ADC

■ Problem Definition

In free running mode, there can be a variation of up to 7 LSB in the digital output of SAR10 ADC.

■ Parameters Affected

Code Variation. This is not a specified parameter.

It is defined as the number of unique output codes generated by the ADC for a given constant input voltage, in addition to the correct code. For example, for an input voltage of 2.000 V, the expected code is 190hex and the ADC generates three codes: 191hex, 190hex, and 192hex. The code variation is 2 LSB.

■ Trigger Condition(S)

SAR10 ADC is configured in the free running mode. When ADC is operated in free running mode, for a constant input voltage output of ADC can have a variation of up to 7LSB. This can be resolved by using the averaging technique or by disabling the free running mode before reading the data and enabling again after reading the data.

■ Scope of Impact

Inaccurate output is possible.

■ Workaround

This issue can be averted by using one or both of the following workarounds. Consult a Cypress representative for additional assistance.

- Use the averaging technique. That is, take multiple samples of the input, and use a digital averaging filter.
- Disable the free running mode before reading data out, and enable the free running mode after completing the read operation.

■ Fix Status

No silicon fix is planned.

Document History Page

Document Title: CY8C21345/CY8C21645/CY8C22345/CY8C22345H/CY8C22645, Automotive PSoC® Programmable System-on-Chip™ Document Number: 001-55397				
Revision	**ECN**	**Orig. of Change**	**Submission Date**	**Description of Change**
**	2759868	VIVG	09/04/09	New data sheet.
*A	2788690	VIVG	10/20/09	Added 48 SSOP to the marketing part numbers. Corrected the I_{SOA} spec in table 13/14. Changed the ThetaJA values based on PE inputs.
*B	2792800	VIVG	10/26/09	Corrected typo in ordering information table (Digital I/O for 48-SSOP devices)
*C	2822630	BTK	12/07/09	Added CY8C22345H devices and updated Features section and PSoC Functional Overview section to include haptics device information. Updated Features section. Added Contents section. Updated PSoC Functional Overview section. Updated Block Diagram of device. Updated PSoC Device Characteristics table. Updated Pinouts section. Fixed issues with the Register Map tables. Added a figure for SLIMO configuration. Updated footnotes for the DC Programming Specifications table. Corrected $V_{DDIWRITE}$ and $Flash_{ENT}$ electrical specifications. Updated Ordering Information section. Added Development Tool Selection section. Combined 5 V DC Operational Amplifier Specifications table with 3.3 V DC Operational Amplifier Specifications table. Updated all AC specifications to conform to 5% IMO accuracy and 8.33% SLIMO accuracy. Split up electrical specifications for A-grade and E-grade devices in the Absolute Maximum Ratings, Operating Temperature, DC Chip Level Specifications, DC Programming Specifications, and AC Chip-Level Specifications tables. Added Solder Reflow Peak Temperature table. Added T_{PRGH}, T_{PRGC}, I_{OL}, I_{OH}, F_{32KU}, DC_{ILO}, and $T_{POWERUP}$ electrical specifications. Added maximum values and updated typical values for T_{ERASEB} and T_{WRITE} electrical specifications. Replaced T_{RAMP} electrical specification with $SR_{POWERUP}$ electrical specification.
*D	2905459	NJF	04/06/10	Updated Cypress website links Added $T_{BAKETEMP}$, $T_{BAKETIME}$, and Fout48M electrical specifications Removed sections ‘Third Party Tools’ ‘Build a PSoC Emulator into your Board’ Updated package diagrams Updated Ordering Information table Updated Solder Reflow Peak Temperature specifications. Updated the Getting Started and Designing with PSoC Designer sections. Converted data sheet from Preliminary to Final Deleted 5% oscillator accuracy reference in the Features section. Deleted reference to a specific SAR10 ADC sample rate in the Analog System section. Updated the following Electrical Specifications: I_{DD}, I_{SB}, I_{SBXTL}, V_{REF}, V_{CMOA}, I_{ADCREF}, INL_{ADC}, DNL_{ADC}, V_{PPOR2}, $Flash_{DR}$, F_{IMO24}, T_{RiseF}, T_{FallF}, T_{RiseS}, T_{FallS}. Deleted the SPS_{ADC} electrical specification, the DC Low Power Comparator Specifications, the AC Low Power Comparator Specifications, and the AC Analog Mux Bus Specifications.
*E	2915673	VIVG	04/16/10	Post to external web
*F	2991841	BTK	07/23/10	Added a clarifying note to the V_{PPOR1} electrical specification. Added CY8C22345-12PVXE(T) devices. Moved Document Conventions to the end of the document.
*G	3037161	BTK	09/23/10	Added CY8C21345-12PVXE(T) devices to the Ordering Information section.
*H	3085024	BTK	11/12/10	Added CY8C21645-12PVXE(T), CY8C21645-24PVXA(T), CY8C22645-12PVXE(T), and CY8C22645-24PVXA(T) devices to the Ordering Information section.
*I	3200275	BTK	03/18/11	Added tape and reel packaging information.